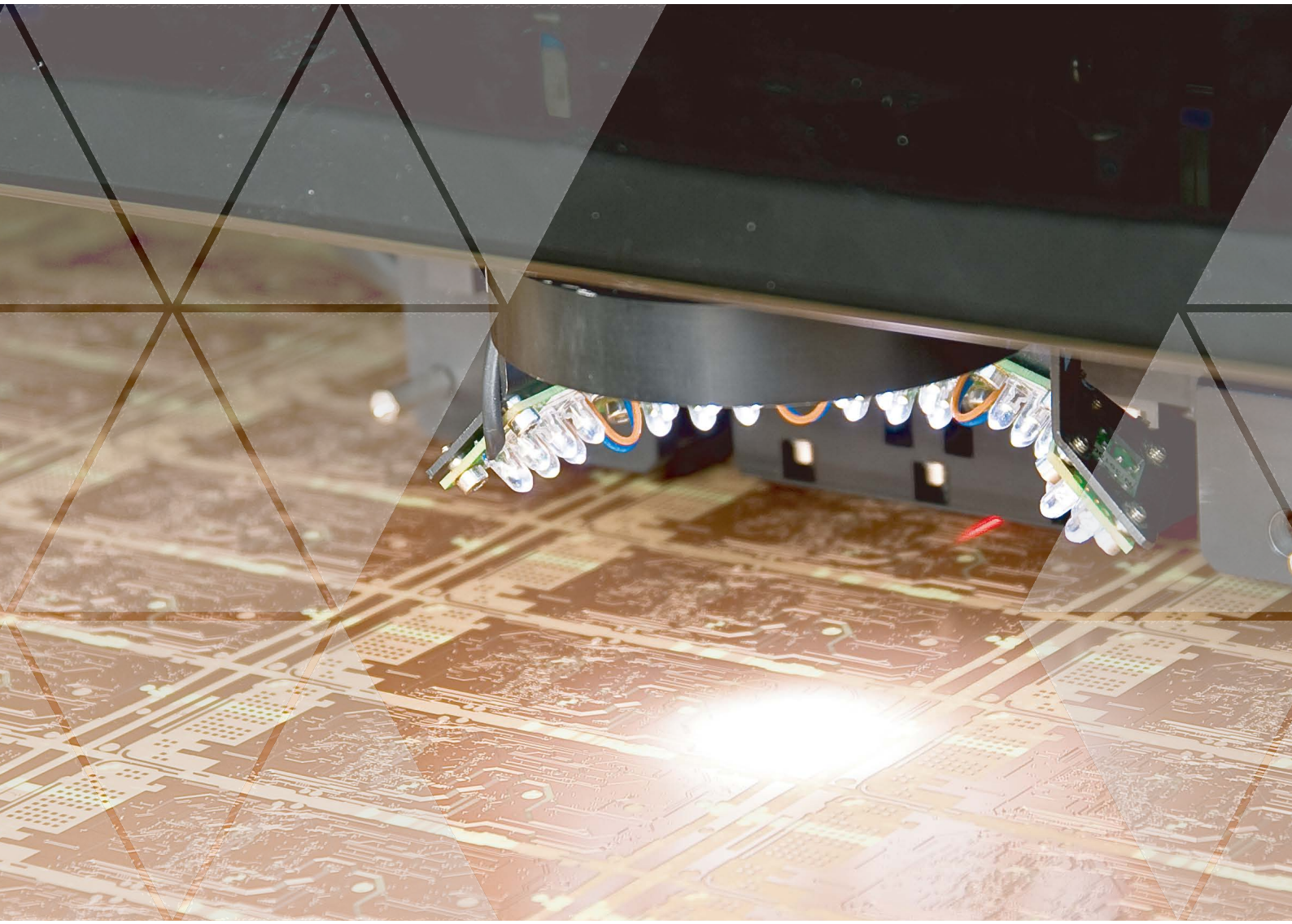
Phoenix HDI



CIMS
By Camtek technology

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Phoenix HDI

PCB technology	Down to 30µm line/space
Throughput	Up to 220 sides/hour, 18"× 24" (457mm × 610mm)
Panel Size (maximum)	30"× 26" (762mm × 660mm)
Panel Thickness Range	1mil - 200mil (0.025mm - 5mm)
Panel Types and Designs	Inner and outer layers, build-up and sequential lamination layers including Signal, Mix and P&G, Cross-Shield, Laser drilled layers
Materials Inspected	All copper foil types; Plated copper; Gold Plating; Silver-Halide and Diazo; Photo-Resist; Teflon and Ceramic; DSTF, DT and other low contrast materials
Detectable Defect Types	Open and short circuit, Nick, Protrusion, Mouse-bite, Pinhole, Island, Dish-down, Line/Space width violation , Annular ring violation, Extra and Missing features
Reference Source Data	CAM
Tooling	Pin-less
Operating System	Windows 7™ 64bit
Detection and set-up engine	Powered by Spark™
AMHS	The Phoenix can be connected to AMHS
Verification and Repair Methods	Offline verification station
Dimensions	Height – 68.5" (174cm) Width – 67.7" (172cm) Depth – 93.3" (237cm) Weight – 1550Kg Power – 200±10%VAC; 50/60Hz; 2.5Kw
Compressed Air	6ATM, 1L/min
Temperature and Humidity	22±3°C; 50±10%RH

Optional Features	+2DM – panel dimensions measurement	Fi – final inspection
	+2CD – 2D measurement of circuit elements	LDI – laser drill inspection
	CDB/CDBIC – defects classification and virtual defects mapping	VVS – virtual verification system

Powered by SPARK 2.0

Powered by Microlight

Powered by Spark™

- Superior detection
- Lowest false calls rate
- Simple and quick setup
- Fast adaptation cycle

Powered by Microlight™

Advanced illumination technology provides:

- Flexible light coverage to detect fine shorts and dishdowns
- A full spectrum of waves' length suitable to all type of materials
- Adaptability for special applications